

### IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning on page 4, line 22 is amended as follows:

B1  
As shown in FIG. 7, the method further includes coupling assembly 30 to integrated circuit 10. Integrated circuit 10 and assembly 30 are coupled together by flipping either integrated circuit 10 or assembly 30 over and overlaying the respective rings 38, 52. Ring 52 and ring 38 need to overlap around the entire circumference of the rings 38, 52 in order to form a sealed cavity 60 as the solder bonds the rings 38, 52 together. Once the rings 38, 52 are bonded together, the MEMS device 32 is positioned within the sealed cavity 60. Electrical signals may be transferred back and forth between MEMS device 32 and wires 59. In an example embodiment, the wires 59 are electrically connected to the MEMS device 32 via pads 20, interconnect layers 16A, 16B, 16C, pads 19, solder bumps 51 and ~~pads 59~~ pads 39. The present invention is not to be construed as limited to any particular method of coupling the integrated circuit 10 to the assembly 30, or any particular electrical connection between the MEMS device and other electrical components.